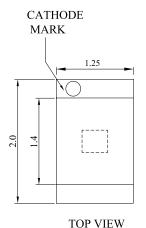
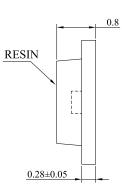
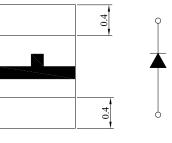
RoHS

Compliant

Package Dimensions:







BOTTOM VIEW

All dimensions are in mm Tolerance: ±0.1mm

Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Rating	Unit
Power Dissipation	PD	78	°C
Reverse Voltage	Vr	5	V
D.C. Forward Current	lf	30	mA
Pulsed Forward Current (1 / 10 Duty Cycle, 0.1ms Pulse Width)	If (Peak)	80	mA
Operating Temperature Range	Topr.	-40 to +80	°C
Storage Temperature Range	Tstg.	-40 to +85	°C
Soldering Temperature	Tsld.	Reflow Soldering: 260°C for 10sec.	

Electrical & Optical Characteristics: Hyper Red

Parameter	Symbol	Condition	Min.	Тур.	Max.	Unit
Luminous Intensity	lv	lf = 20mA	-	11	-	mcd
Forward Voltage	Vf	lf = 20mA	1.9	-	2.6	V
Peak Wavelength	λр	lf = 20mA	-	567	-	nm
Dominent Wavelength	λd	lf = 20mA	-	572	-	nm
Reverse Current	lr	Vr = 5V	-	-	100	μA
Viewing Angle	20 ½	lf = 20mA	-	140	-	deg
Spectrum Line Halfwidth	Δλ	lf = 20mA	-	30	-	nm

Note: 1. The data is tested by an IS tester

2. Customer's special requirements are also welcome.



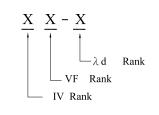
Product Specification

	Specification	Material	Quantity
lv	L: 5.16 – 7.56 mcd M: 7,56 – 11.0 mcd N: 11.0 – 16.5 mcd P: 16.5 – 24.4 mcd @ 20mA	-	-
λd	566 – 577 nm @ 20mA	-	-
Vf	H: 1.9 – 2.2 V J: 2.2 – 2.4 V K: 2.4 – 2.6 V @ 20mA	-	-
lr	< 100µA @ Vr=5V	-	-
Resin	White diffused	Epoxy resin	-
Carrier tape	-	Conductive black tape	4,000pcs per reel
Reel	-	White	-
Label	LT standard	Paper	-
Packing Bag	250mm × 220mm	Aluminium laminated bag	One reel one bag
Carton	LT standard	Paper	Non-specified
Others:		-	*



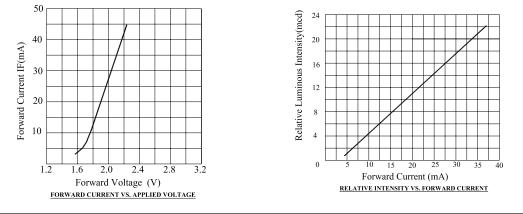
BIN CODE :





Typical Electrical & Optical Characteristics Curves:

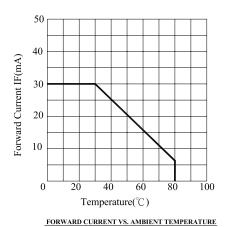
(25°C Ambient temperature unless otherwise noted)

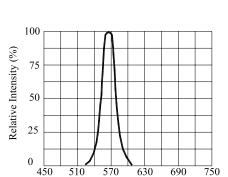




SMD Chip LED

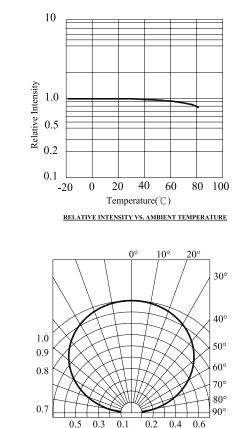
multicomp PRO





Wavelength (nm)

RELATIVE INTENSITY VS. WAVELENGTH



Radiation Diagram

Recommended Storage Environment:

- Temperature: 5°C to 30°C (41°F to 86°F)
- Humidity: 60% RH Max.
- · Use within 7 days after opening of sealed vapour/ESD barrier bags

If moisture absorbent material (silica gel) has faded away or LEDs have exceeded the storage time, baking treatment should be performed using the following conditions:

- Baking Treatment : 60 ± 5°C for 24 hours
- Fold the opened bag firmly and keep in dry environment



SMD Chip LED

multicomp PRO

Reflow Soldering

Recommended use of upper and lower heater type reflow furnace.

- · 260°C max for up to 10 seconds, one time only
- Pre-heat is 150°C max for up to 2 minutes max
- In case of screen-printing, keep metal mask thickness between 0.2mm and 0.3mm

Cleaning

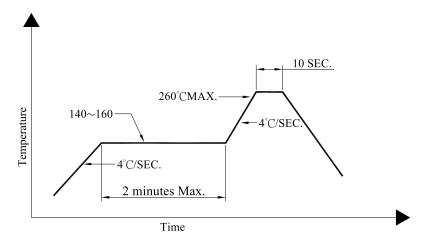
Surface condition of this device may change when organic solvents such as trichloroethylene or acetone were applied.

- · Avoid using organic solvent
- Recommend ultrasonic method 300W max.

Packaging

- · EIA-481A standard package
- · In 8mm tape on 4000pcs diameter reels sealed in vapour/ESD barrier bags

Reflow Temp / Time:



Part Number Table

LED Chip		Lens Colour	Part Number	
Material	Emitting Colour	Lens Colour	Part Number	
GaP / GaP	Green	White diffused	703-0104	

Important Notice : This data sheet and its contents (the "Information") belong to the members of the AVNET group of companies (the "Group") or are licensed to it. No licence is granted for the use of it other than for information purposes in connection with the products to which it relates. No licence of any intellectual property rights is granted. The Information is subject to change without notice and replaces all data sheets previously supplied. The Information supplied is believed to be accurate but the Group assumes no responsibility for its accuracy or completeness, any error in or omission from it or for any use made of it. Users of this data sheet should check for themselves the Information and the suitability of the products for white any assumptions based on information included or omitted. Liability for loss or damage resulting from any reliance on the Information or use of it (including liability resulting from negligence or where the Group was aware of the possibility of such loss or damage arising) is excluded. This will not operate to limit or restrict the Group's liability for death or personal injury resulting from its negligence. Multicomp Pro is the registered trademark of Premier Farnell Limited 2019.

